	Material Composit © Copyright 2005. IPC, 1 international and Pan-An	Bannockb	urn, Illinois. A	ll rights reserved utions.	under both	This docume level parts, t	ent is a declarat	ion of the su encompasse	ubstances v s all lower	within the manufacture level materials for w	rer listed it which the m	em. Note: anufacture	if the item is an as er has engineering	sembly with low responsibility.
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information			
Supplier Informa	tion													
Company name*			Company unique ID			Unique ID Authority				Response Date*				
onsemi											2024-05-18			
Contact Name			Title - Contact				Phone - Contact*				Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative				Phone - Representative*				Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Requester	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Date Version Manufacturing Site		Ianufacturing Site	1	Weight*	UOM	Unit Type	
		NVTFS5C658NLTAG AFSN		AFSM T6 60V LL u8FL		2024-05-18		N	MY1		29.38	mg	Each	
Ianufacturing P	roccess Information	1									L			
Terminal Plating / Grid Array Material Termi			rminal Base Alloy J-STD-020 MSL R			L Rating	Peak Process Body Temperature Max Time at Peak			Temperature Number of Reflow Cycles				
Matte Tin (Sn) - annealed CU All			CU Alloy	1			260 C 30			seconds 3				
omments														
vel 1 - maximum tim	ie at peak temperature d	luring sol	dering is 10-30	) seconds										
or more information	regarding material com	position	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).								
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature	astislav Drska	Le									

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	0.38	mg	Supplier	Zinc (Zn)	7440-66-6		0.0005	mg
			Supplier	Iron (Fe)	7439-89-6		0.0089	mg
			Supplier	Copper (Cu)	7440-50-8		0.3705	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0001	mg
Die	0.3	mg	Supplier	Silicon (Si)	7440-21-3		0.3	mg
Die Attach Solder	0.65	mg	Supplier	Silver (Ag)	7440-22-4		0.0162	mg
			А	Lead (Pb)	7439-92-1	7a	0.6012	mg
			Supplier	Tin (Sn)	7440-31-5		0.0325	mg
Lead Frame	12.41	mg	Supplier	Silver (Ag)	7440-22-4		0.0074	mg
			Supplier	Iron (Fe)	7439-89-6		0.0124	mg
			Supplier	Copper (Cu)	7440-50-8		12.3864	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0037	mg
Iold Compound-Black	15.0	mg		Epoxy resin	proprietary data		1.125	mg
			Supplier	Phenolic Resin	Proprietary Data		0.375	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.125	mg
			Supplier	Carbon Black (C)	1333-86-4		0.075	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		12.3	mg
Plating	0.6	mg	Supplier	Tin (Sn)	7440-31-5		0.6	mg
Wire Bond - Cu	0.04	mg	Supplier	Copper (Cu)	7440-50-8		0.04	mg